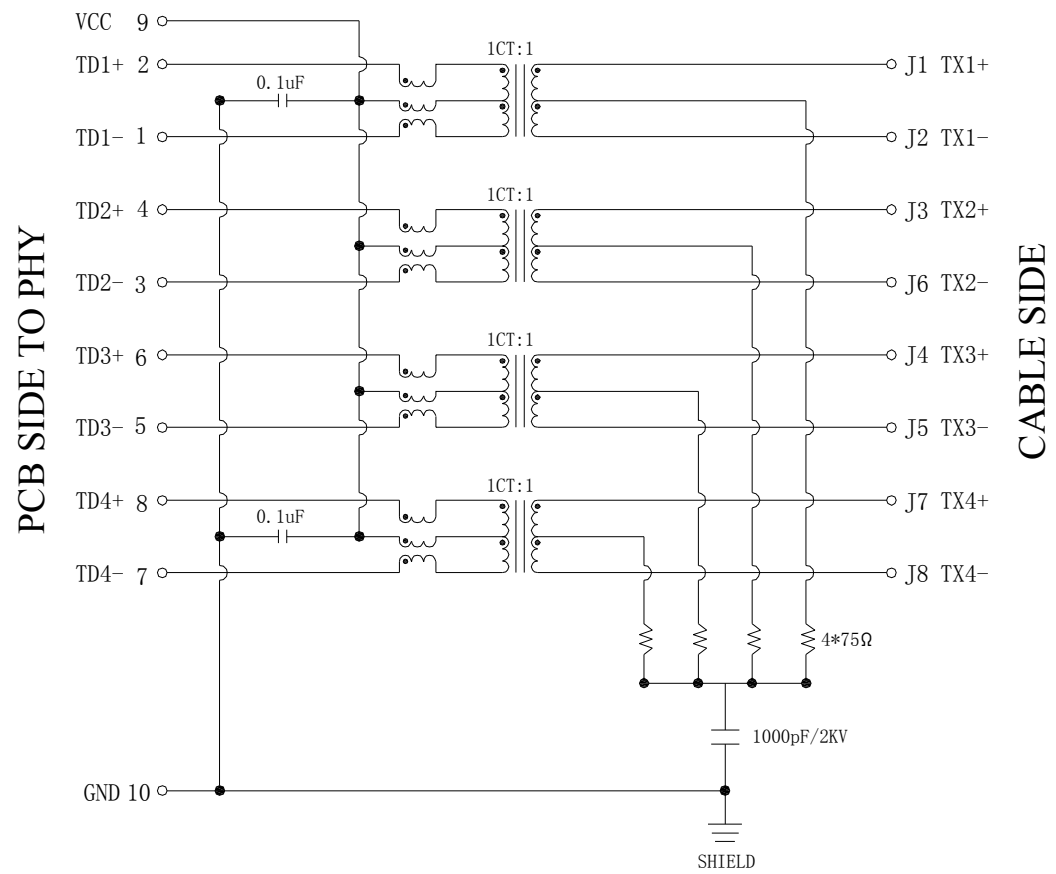


REACH & RoHS
COMPLIANT

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.10.12



Electrical:

- Turn ratio: 2~1: J1~J2 = 1CT:1CT(±2%).
4~3: J3~J6 = 1CT:1CT(±2%).
6~5: J4~J5 = 1CT:1CT(±2%).
8~7: J7~J8 = 1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;
-1 6dB Min 10~30MHz.
-1 2dB Min 30~60MHz.
-10dB Min 60~80MHz.
- Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
- CMR: -35dB Min 1~100MHz;
- Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

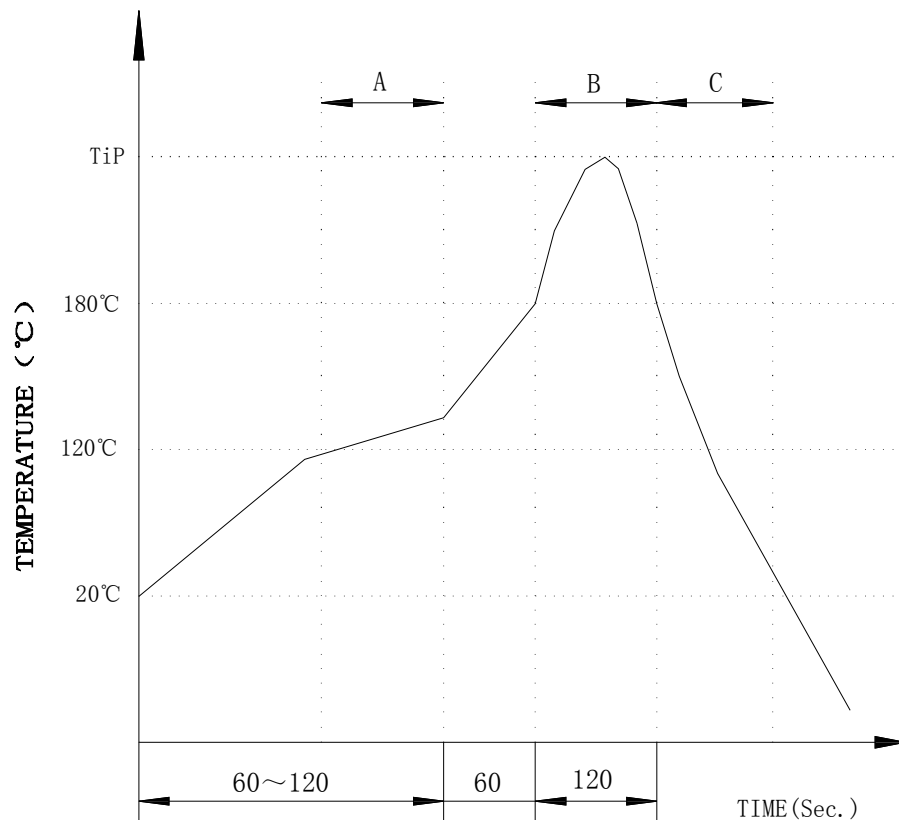
CELION SAS

TITLE: RJ45 2X1 1000BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
	PART NO.: 21Q152HWA2D057	SACLE 1:1	REV A0	x±0.35 .x±0.30	x°±3.0° .x°±2.0°
	REMARK:	SHEET 2/3		.xx±0.25 .xxx±0.10	.xx°±1.5° .xxx°±1.0°
					CHECKED BY: TW.Xu
					DESIGND BY: MQ.Qu

REACH & RoHS
COMPLIANT

PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.10.12



A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

CELION SAS

TITLE:
RJ45 2X1 1000BASE

SIZE
A4

UNITS
MM[INCH]

GENERAL TOLERANCES
UNLESS SPECIFIED

APPROVED BY:
JP.Gong

PART NO.:
21Q152HWA2D057

SACLE
1:1

REV
A0

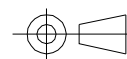
$x \pm 0.35$
 $.x \pm 0.30$

$x^\circ \pm 3.0^\circ$
 $.x^\circ \pm 2.0^\circ$

CHECKED BY:
TW.Xu

REMARK:

SHEET
3/3



$.xx \pm 0.25$
 $.xxx \pm 0.10$

$.xx^\circ \pm 1.5^\circ$
 $.xxx^\circ \pm 1.0^\circ$

DESIGND BY:
MQ.Qu